


# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

1.1 Company	 STMicroelectronics International N.V.
1.2 PCN No.	MDG/23/14399
1.3 Title of PCN	Introduction of plasma dicing for CMOSF8H+ industrial grade EEPROM
1.4 Product Category	M24C02-WMN6TP M24C02-RMN6TP M24C02-FMN6TP M24C04-WMN6TP M24C04-RMN6TP M24C04-FMN6TP
1.5 Issue date	2023-11-17

## 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
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2.2 Change responsibility	
2.2.1 Product Manager	Marie-France FLORENTIN
2.1.2 Marketing Manager	Sylvain FIDELIS
2.1.3 Quality Manager	Mickael DENAIS-ALLICHON

## 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Process flow chart: Revision change in Process (process technology, sawing, die attach, plasma, capillary, marking, packing, labelling, transportation, etc..)	ST Shenzhen (China)

## 4. Description of change

	Old	New
4.1 Description	The CMOSF8H+ process technology running in ST Rousset (France) 8 inches fab (R8) ...	... benefits of introduction of plasma dicing technology before assembly of SO8N.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	- Form: no change - Fit: no change - Function: no change	

## 5. Reason / motivation for change

5.1 Motivation	Plasma dicing allows capacity improvement and better die singulation quality. All the M24C04, M24C02 industrial grade EEPROM currently produced with CMOSF8H+ process technology will benefit from this change.
5.2 Customer Benefit	CAPACITY INCREASE

## 6. Marking of parts / traceability of change

6.1 Description	N/A
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## 7. Timing / schedule

7.1 Date of qualification results	2023-11-15
7.2 Intended start of delivery	2024-02-15
7.3 Qualification sample available?	Upon Request

## 8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)		
14399 Public product.pdf 14399 PCN PLASMA DICING CMOSF8H+.pdf		

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24C02-FMN6TP	
	M24C02-RMN6TP	
	M24C02-WMN6TP	
	M24C04-FMN6TP	
	M24C04-RMN6TP	
	M24C04-WMN6TP	

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